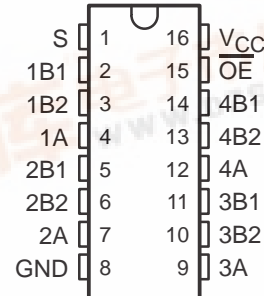


# 4-BIT 1-OF-2 FET MULTIPLEXER/DEMULTIPLEXER 5-V BUS SWITCH WITH –2-V UNDERSHOOT PROTECTION

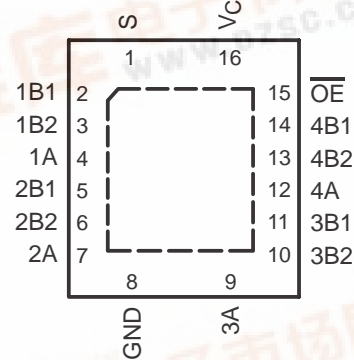
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- Undershoot Protection for Off-Isolation on A and B Ports Up To –2 V
- Bidirectional Data Flow, With Near-Zero Propagation Delay
- Low ON-State Resistance ( $r_{on}$ ) Characteristics ( $r_{on} = 3\ \Omega$  Typical)
- Low Input/Output Capacitance Minimizes Loading and Signal Distortion ( $C_{io(OFF)} = 5.5\text{ pF}$  Typical)
- Data and Control Inputs Provide Undershoot Clamp Diodes
- Low Power Consumption ( $I_{CC} = 3\ \mu\text{A}$  Max)
- $V_{CC}$  Operating Range From 4 V to 5.5 V
- Data I/Os Support 0 to 5-V Signaling Levels (0.8-V, 1.2-V, 1.5-V, 1.8-V, 2.5-V, 3.3-V, 5-V)
- Control Inputs Can be Driven by TTL or 5-V/3.3-V CMOS Outputs
- $I_{off}$  Supports Partial-Power-Down Mode Operation
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Performance Tested Per JESD 22
  - 2000-V Human-Body Model (A114-B, Class II)
  - 1000-V Charged-Device Model (C101)
- Supports I<sup>2</sup>C Bus Expansion
- Supports Both Digital and Analog Applications: USB Interface, Bus Isolation, Low-Distortion Signal Gating

D, DB, DBQ, OR PW PACKAGE  
(TOP VIEW)



RGY PACKAGE  
(TOP VIEW)



## description/ordering information

### ORDERING INFORMATION

T <sub>A</sub>	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	QFN – RGY	Tape and reel	SN74CBT3257CRGYR	CU257C
		Tube	SN74CBT3257CD	CBT3257C
	SOIC – D	Tape and reel	SN74CBT3257CDR	
		Tape and reel	SN74CBT3257CDBR	CU257C
	SSOP (QSOP) – DBQ	Tape and reel	SN74CBT3257CDBQR	CU257C
		Tape and reel	SN74CBT3257CPW	CU257C
	TSSOP – PW	Tube	SN74CBT3257CPW	
		Tape and reel	SN74CBT3257CPWR	

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

# SN74CBT3257C

## 4-BIT 1-OF-2 FET MULTIPLEXER/DEMULTIPLEXER

### 5-V BUS SWITCH WITH –2-V UNDERSHOOT PROTECTION

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#### description/ordering information (continued)

The SN74CBT3257C is a high-speed TTL-compatible FET multiplexer/demultiplexer with low ON-state resistance ( $r_{ON}$ ), allowing for minimal propagation delay. Active Undershoot-Protection Circuitry on the A and B ports of the SN74CBT3257C provides protection for undershoot up to –2 V by sensing an undershoot event and ensuring that the switch remains in the proper OFF state.

The SN74CBT3257C is a 4-bit 1-of-2 multiplexer/demultiplexer with a single output-enable ( $\overline{OE}$ ) input. The select (S) input controls the data path of the multiplexer/demultiplexer. When  $\overline{OE}$  is low, the multiplexer/demultiplexer is enabled and the A port is connected to the B port, allowing bidirectional data flow between ports. When  $\overline{OE}$  is high, the multiplexer/demultiplexer is disabled and a high-impedance state exists between the A and B ports.

This device is fully specified for partial-power-down applications using  $I_{off}$ . The  $I_{off}$  feature ensures that damaging current will not backflow through the device when it is powered down. The device has isolation during power off.

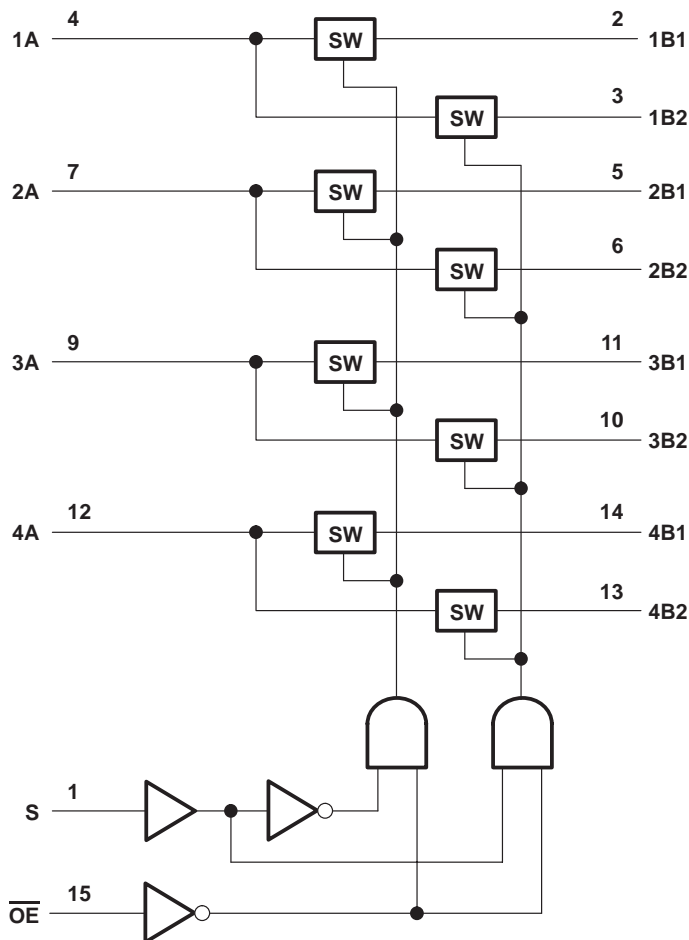
To ensure the high-impedance state during power up or power down,  $\overline{OE}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

FUNCTION TABLE

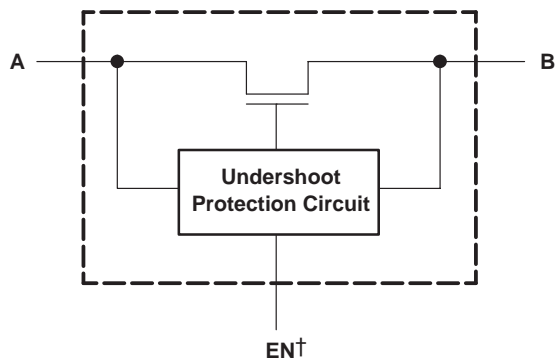
INPUTS		INPUT/OUTPUT A	FUNCTION
$\overline{OE}$	S1		
L	L	B1	A port = B1 port
L	H	B2	A port = B2 port
H	X	Z	Disconnect

**SN74CBT3257C**  
**4-BIT 1-OF-2 FET MULTIPLEXER/DEMULTIPLEXER**  
**5-V BUS SWITCH WITH -2-V UNDERSHOOT PROTECTION**  
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logic diagram (positive logic)



simplified schematic, each FET switch (SW)



† EN is the internal enable signal applied to the switch.

# SN74CBT3257C

## 4-BIT 1-OF-2 FET MULTIPLEXER/DEMULTIPLEXER

### 5-V BUS SWITCH WITH –2-V UNDERSHOOT PROTECTION

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#### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†</sup>

Supply voltage range, $V_{CC}$	–0.5 V to 7 V
Control input voltage range, $V_{IN}$ (see Notes 1 and 2)	–0.5 V to 7 V
Switch I/O voltage range, $V_{I/O}$ (see Notes 1, 2, and 3)	–0.5 V to 7 V
Control input clamp current, $I_{IK}$ ( $V_{IN} < 0$ )	–50 mA
I/O port clamp current, $I_{I/OK}$ ( $V_{I/O} < 0$ )	–50 mA
ON-state switch current, $I_{I/O}$ (see Note 4)	±128 mA
Continuous current through $V_{CC}$ or GND terminals	±100 mA
Package thermal impedance, $\theta_{JA}$ (see Note 5): D package	73°C/W
(see Note 5): DB package	82°C/W
(see Note 5): DBQ package	90°C/W
(see Note 5): PW package	108°C/W
(see Note 6): RGY package	39°C/W
Storage temperature range, $T_{stg}$	–65°C to 150°C

<sup>†</sup> Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES:
1. All voltages are with respect to ground unless otherwise specified.
  2. The input and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
  3.  $V_I$  and  $V_O$  are used to denote specific conditions for  $V_{I/O}$ .
  4.  $I_I$  and  $I_O$  are used to denote specific conditions for  $I_{I/O}$ .
  5. The package thermal impedance is calculated in accordance with JESD 51-7.
  6. The package thermal impedance is calculated in accordance with JESD 51-5.

#### recommended operating conditions (see Note 7)

	MIN	MAX	UNIT
$V_{CC}$ Supply voltage	4	5.5	V
$V_{IH}$ High-level control input voltage	2	5.5	V
$V_{IL}$ Low-level control input voltage	0	0.8	V
$V_{I/O}$ Data input/output voltage	0	5.5	V
$T_A$ Operating free-air temperature	–40	85	°C

NOTE 7: All unused control inputs of the device must be held at  $V_{CC}$  or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

**SN74CBT3257C**  
**4-BIT 1-OF-2 FET MULTIPLEXER/DEMULTIPLEXER**  
**5-V BUS SWITCH WITH –2-V UNDERSHOOT PROTECTION**

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**electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)**

PARAMETER		TEST CONDITIONS		MIN	TYP†	MAX	UNIT
$V_{IK}$	Control inputs	$V_{CC} = 4.5\text{ V}$ ,	$I_{IN} = -18\text{ mA}$			–1.8	V
$V_{IKU}$	Data inputs	$V_{CC} = 5\text{ V}$ ,	$0\text{ mA} > I_I \geq -50\text{ mA}$ , $V_{IN} = V_{CC}$ or GND, Switch OFF			–2	V
$I_{IN}$	Control inputs	$V_{CC} = 5.5\text{ V}$ ,	$V_{IN} = V_{CC}$ or GND			$\pm 1$	$\mu\text{A}$
$I_{OZ}^{\ddagger}$		$V_{CC} = 5.5\text{ V}$ ,	$V_O = 0$ to $5.5\text{ V}$ , $V_I = 0$ , Switch OFF, $V_{IN} = V_{CC}$ or GND			$\pm 10$	$\mu\text{A}$
$I_{off}$		$V_{CC} = 0$ ,	$V_O = 0$ to $5.5\text{ V}$ , $V_I = 0$			10	$\mu\text{A}$
$I_{CC}$		$V_{CC} = 5.5\text{ V}$ ,	$I_{I/O} = 0$ , $V_{IN} = V_{CC}$ or GND, Switch ON or OFF			3	$\mu\text{A}$
$\Delta I_{CC}^{\S}$	Control inputs	$V_{CC} = 5.5\text{ V}$ ,	One input at $3.4\text{ V}$ , Other inputs at $V_{CC}$ or GND			2.5	mA
$C_{in}$	Control inputs	$V_{IN} = 3\text{ V}$ or 0			3.5		pF
$C_{io}(\text{OFF})$	A port	$V_{I/O} = 3\text{ V}$ or 0, Switch OFF, $V_{IN} = V_{CC}$ or GND			8.5		pF
	B port				5.5		pF
$C_{io}(\text{ON})$		$V_{I/O} = 3\text{ V}$ or 0, Switch ON, $V_{IN} = V_{CC}$ or GND			16.5		pF
$r_{on}^{\parallel}$		$V_{CC} = 4\text{ V}$ , TYP at $V_{CC} = 4\text{ V}$	$V_I = 2.4\text{ V}$ , $I_O = -15\text{ mA}$		8	12	$\Omega$
		$V_{CC} = 4.5\text{ V}$	$V_I = 0$ , $I_O = 64\text{ mA}$		3	6	
			$I_O = 30\text{ mA}$		3	6	
			$V_I = 2.4\text{ V}$ , $I_O = -15\text{ mA}$		5	10	

$V_{IN}$  and  $I_{IN}$  refer to control inputs.  $V_I$ ,  $V_O$ ,  $I_I$ , and  $I_O$  refer to data pins.

† All typical values are at  $V_{CC} = 5\text{ V}$  (unless otherwise noted),  $T_A = 25^\circ\text{C}$ .

‡ For I/O ports, the parameter  $I_{OZ}$  includes the input leakage current.

§ This is the increase in supply current for each input that is at the specified voltage level, rather than  $V_{CC}$  or GND.

∥ Measured by the voltage drop between the A and B terminals at the indicated current through the switch. ON-state resistance is determined by the lower of the voltages of the two (A or B) terminals.

**switching characteristics over recommended operating free-air temperature range,  $C_L = 50\text{ pF}$  (unless otherwise noted) (see Figure 3)**

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 4\text{ V}$		$V_{CC} = 5\text{ V} \pm 0.5\text{ V}$		UNIT
			MIN	MAX	MIN	MAX	
$t_{pd}^{\#}$	A or B	B or A	0.24		0.15		ns
$t_{pd(s)}$	S	A	6		1.5	5.6	ns
$t_{en}$	S	B	6.3		1.5	5.8	ns
	$\overline{OE}$	A or B	6.3		1.5	5.8	
$t_{dis}$	S	B	6.5		1.5	6	ns
	$\overline{OE}$	A or B	5.9		1.5	5.9	

# The propagation delay is the calculated RC time constant of the typical ON-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

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undershoot characteristics (see Figures 1 and 2)

PARAMETER	TEST CONDITIONS	MIN	TYP†	MAX	UNIT
V <sub>OUTU</sub>	V <sub>CC</sub> = 5.5 V, Switch OFF, V <sub>IN</sub> = V <sub>CC</sub> or GND	2	V <sub>OH</sub> -0.3		V

† All typical values are at V<sub>CC</sub> = 5 V (unless otherwise noted), T<sub>A</sub> = 25°C.

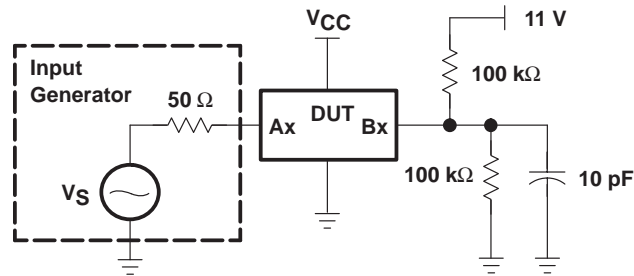


Figure 1. Device Test Setup

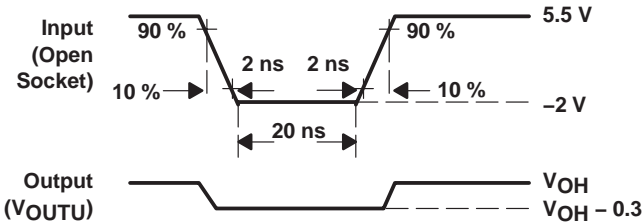
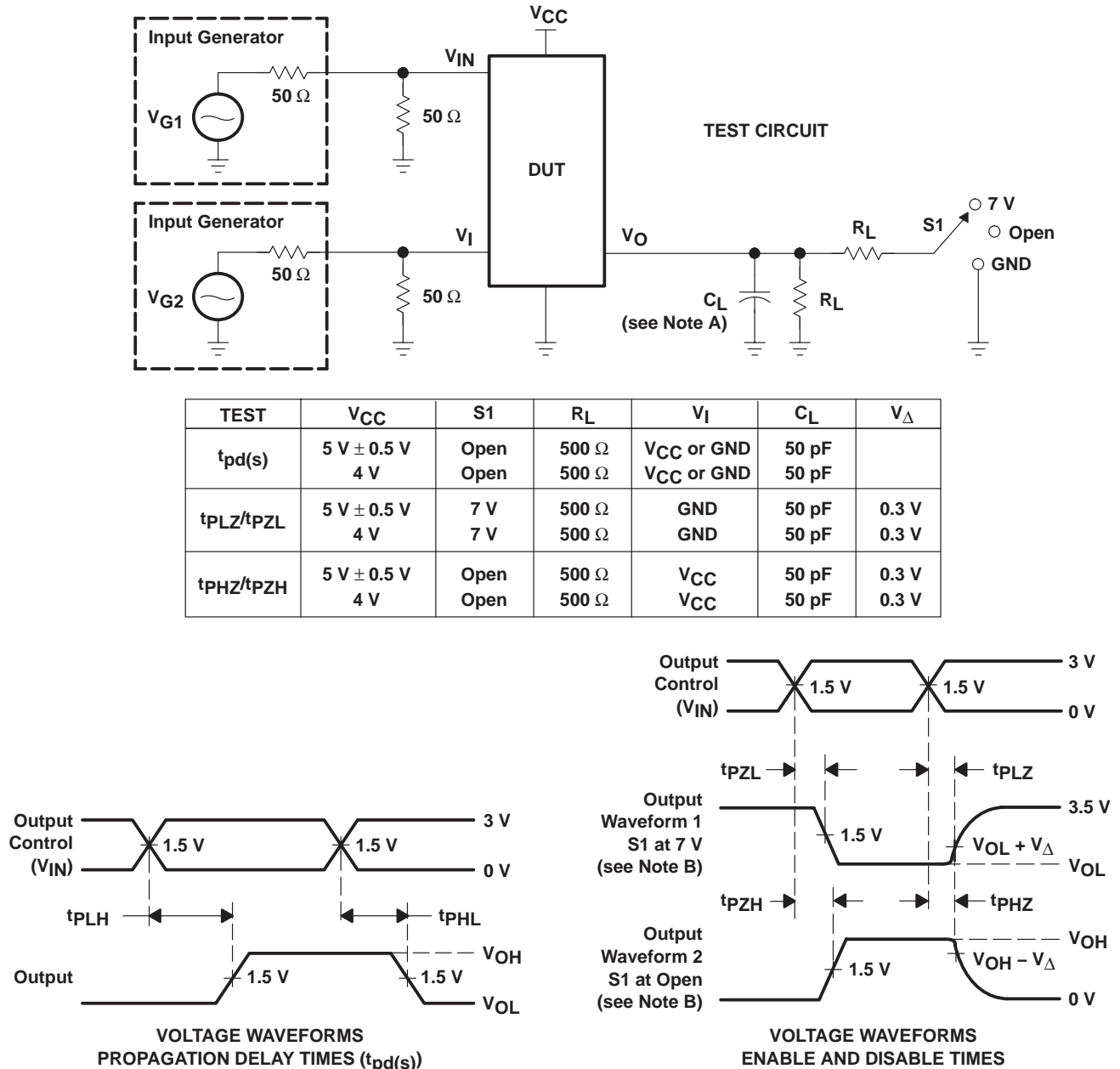


Figure 2. Transient Input Voltage (V<sub>I</sub>) and Output Voltage (V<sub>OUTU</sub>) Waveforms (Switch OFF)

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**4-BIT 1-OF-2 FET MULTIPLEXER/DEMULTIPLEXER**  
**5-V BUS SWITCH WITH -2-V UNDERSHOOT PROTECTION**  
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**PARAMETER MEASUREMENT INFORMATION**



- NOTES:
- A. C<sub>L</sub> includes probe and jig capacitance.
  - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
  - C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z<sub>O</sub> = 50 Ω, t<sub>r</sub> ≤ 2.5 ns, t<sub>f</sub> ≤ 2.5 ns.
  - D. The outputs are measured one at a time with one transition per measurement.
  - E. t<sub>PLZ</sub> and t<sub>PHZ</sub> are the same as t<sub>dis</sub>.
  - F. t<sub>PZL</sub> and t<sub>PZH</sub> are the same as t<sub>en</sub>.
  - G. t<sub>PLH</sub> and t<sub>PHL</sub> are the same as t<sub>pd</sub>(s). The t<sub>pd</sub> propagation delay is the calculated RC time constant of the typical ON-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).
  - H. All parameters and waveforms are not applicable to all devices.

**Figure 3. Test Circuit and Voltage Waveforms**

## PACKAGING INFORMATION

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
SN74CBT3257CD	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74CBT3257CDBQR	ACTIVE	SSOP/QSOP	DBQ	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1YEAR
SN74CBT3257CDBQRE4	ACTIVE	SSOP/QSOP	DBQ	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1YEAR
SN74CBT3257CDBR	ACTIVE	SSOP	DB	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74CBT3257CDBRE4	ACTIVE	SSOP	DB	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74CBT3257CDE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74CBT3257CDR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74CBT3257CDRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74CBT3257CPW	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74CBT3257CPWE4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74CBT3257CPWR	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74CBT3257CPWRE4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74CBT3257CRGYR	ACTIVE	QFN	RGY	16	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1YEAR
SN74CBT3257CRGYRG4	ACTIVE	QFN	RGY	16	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1YEAR

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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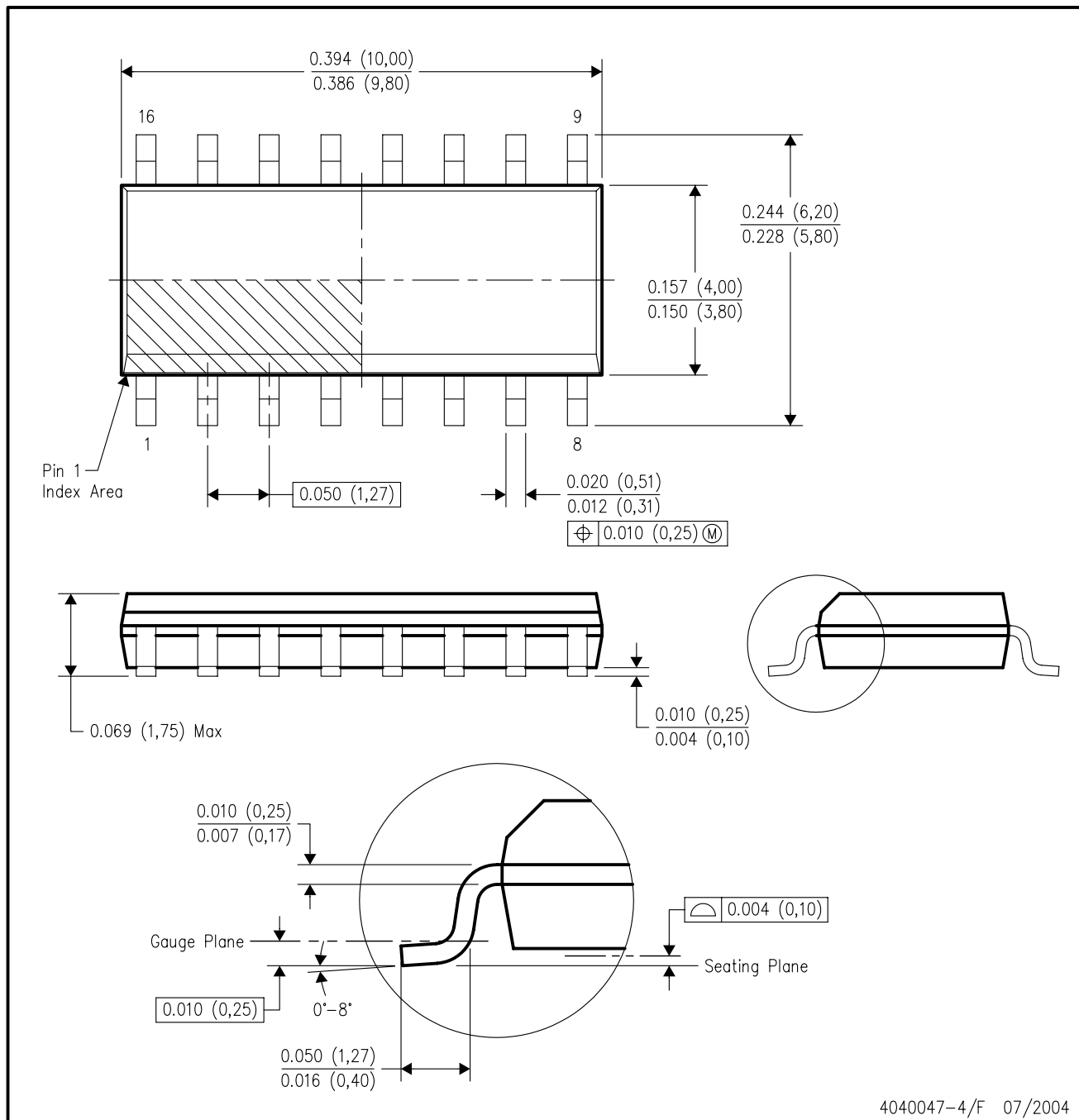
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# MECHANICAL DATA

## D (R-PDSO-G16)

## PLASTIC SMALL-OUTLINE PACKAGE

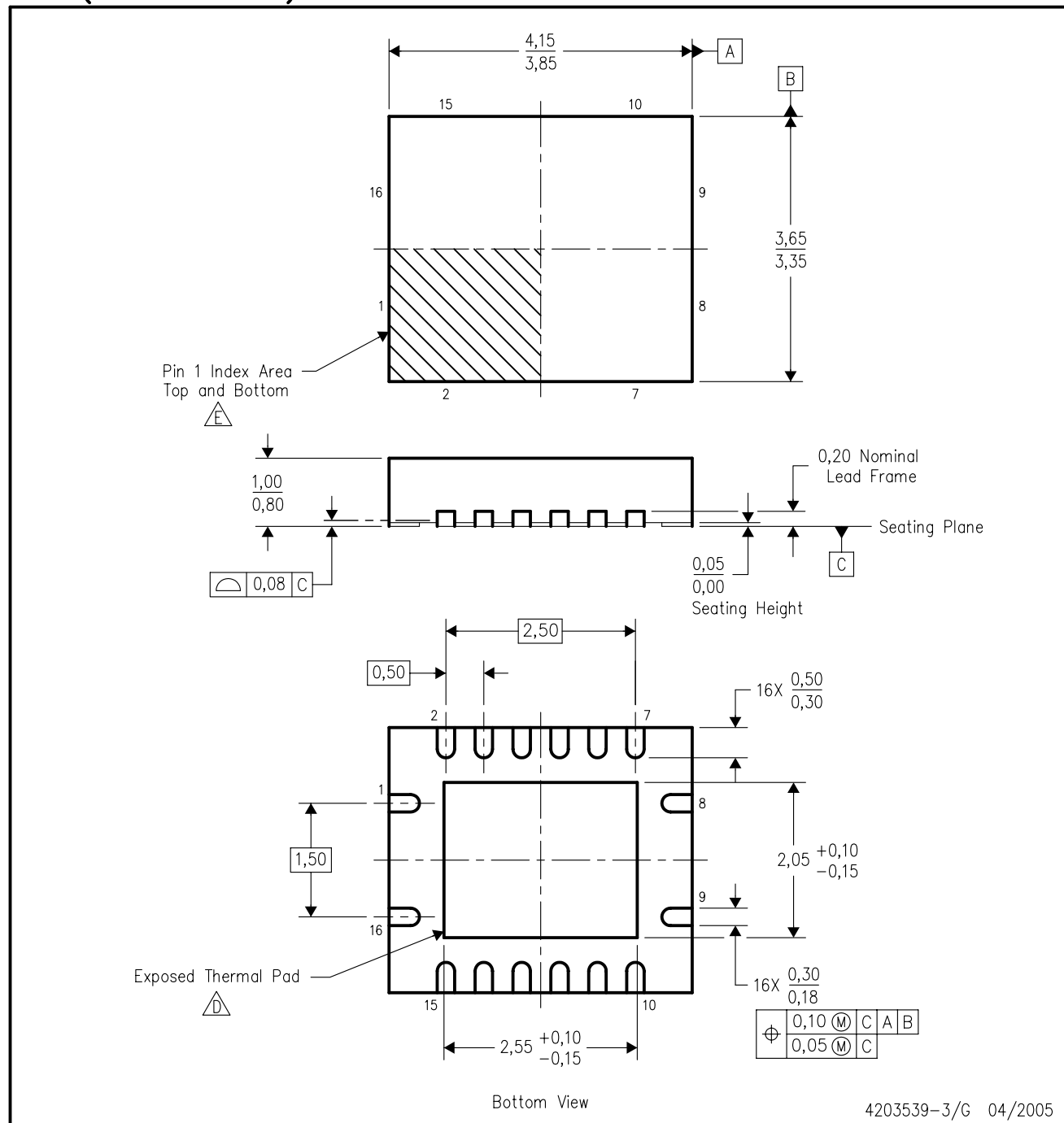


4040047-4/F 07/2004

# MECHANICAL DATA

RGY (R-PQFP-N16)

PLASTIC QUAD FLATPACK

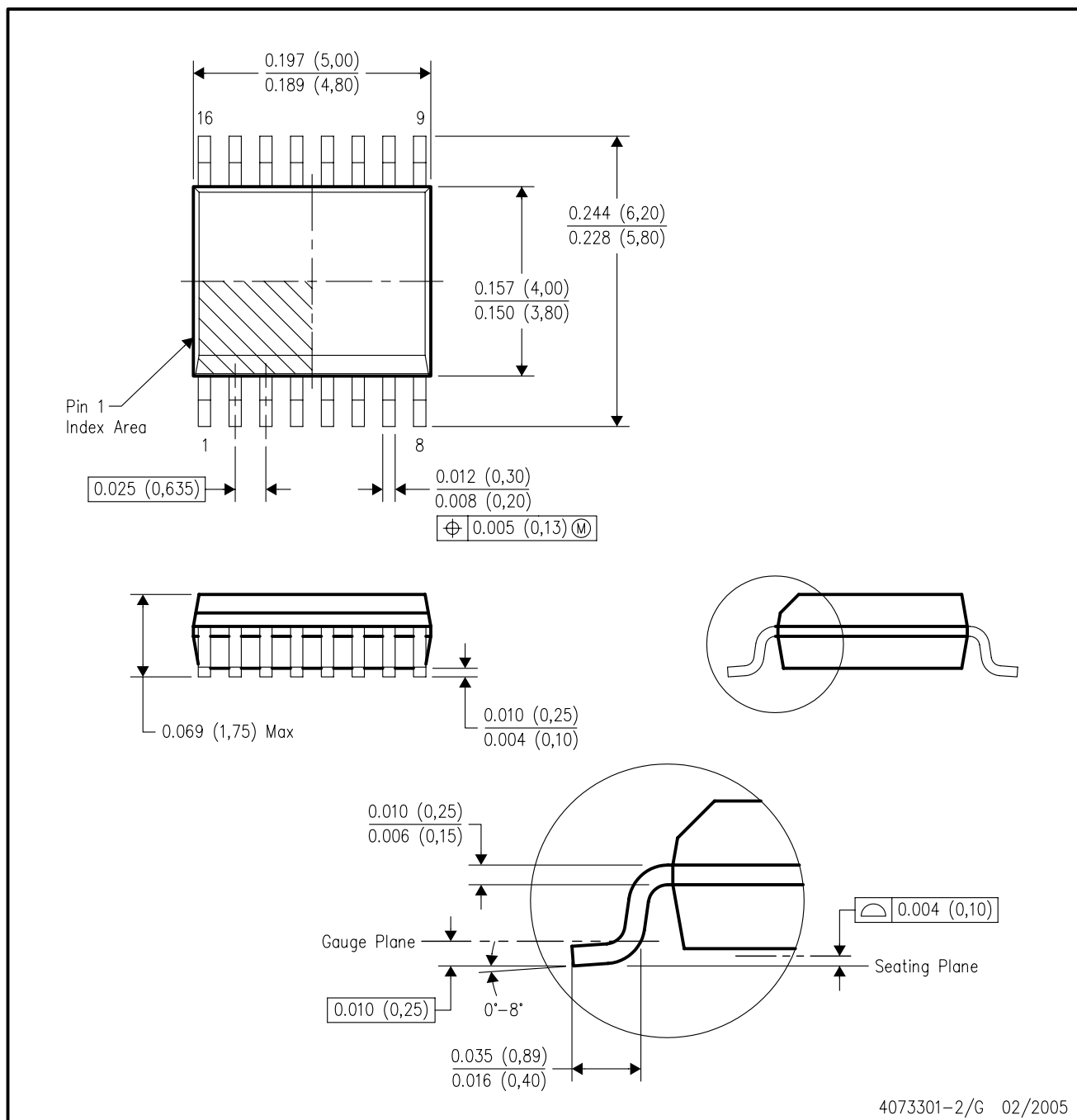


- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
  - B. This drawing is subject to change without notice.
  - C. QFN (Quad Flatpack No-Lead) package configuration.
  - D. The package thermal pad must be soldered to the board for thermal and mechanical performance.
  - E. Pin 1 identifiers are located on both top and bottom of the package and within the zone indicated. The Pin 1 identifiers are either a molded, marked, or metal feature.
  - F. Package complies to JEDEC MO-241 variation BB.

# MECHANICAL DATA

DBQ (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



4073301-2/G 02/2005

- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15) per side.
  - Falls within JEDEC MO-137 variation AB.

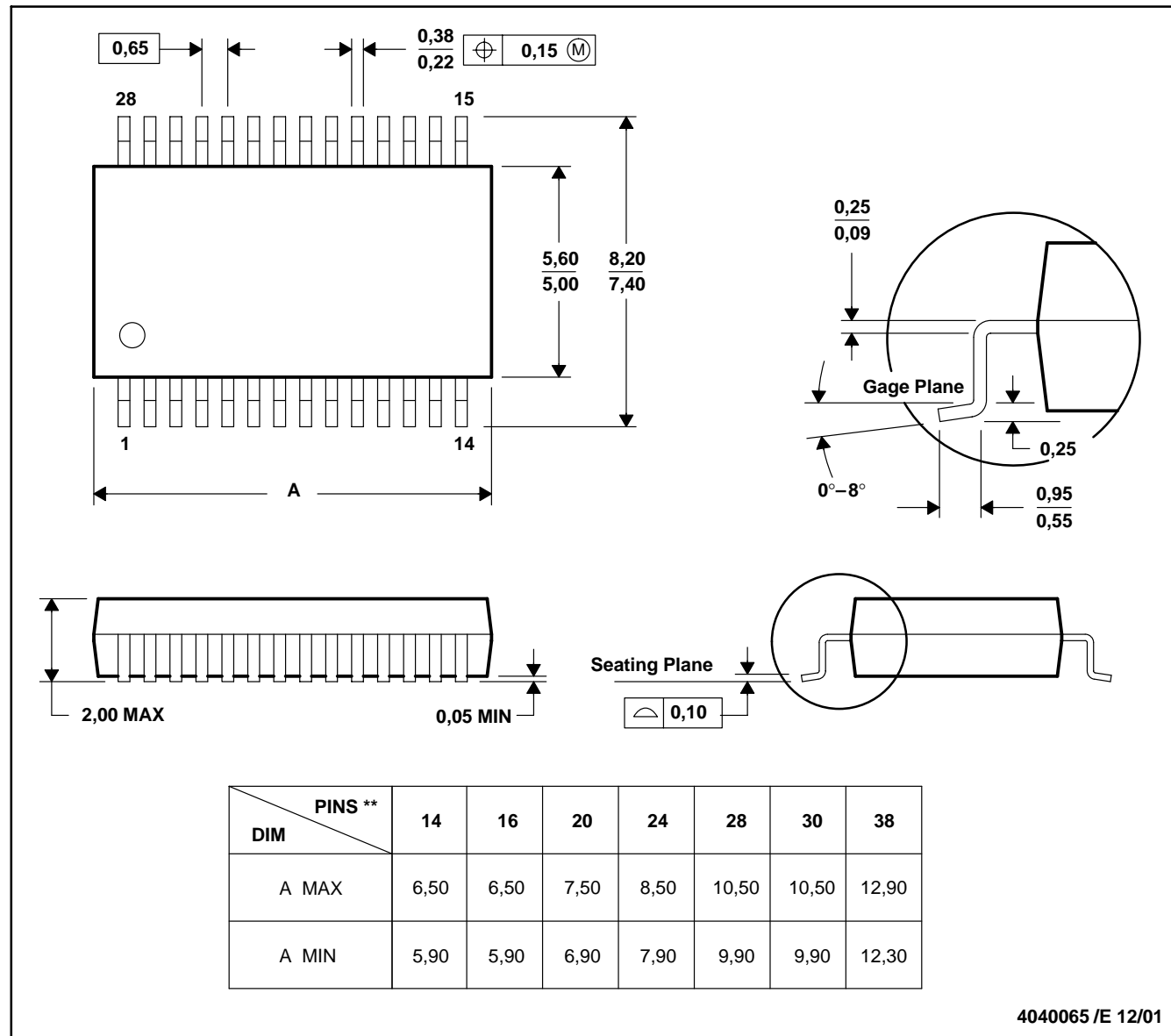
# MECHANICAL DATA

MSS0002E – JANUARY 1995 – REVISED DECEMBER 2001

DB (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
  - D. Falls within JEDEC MO-150

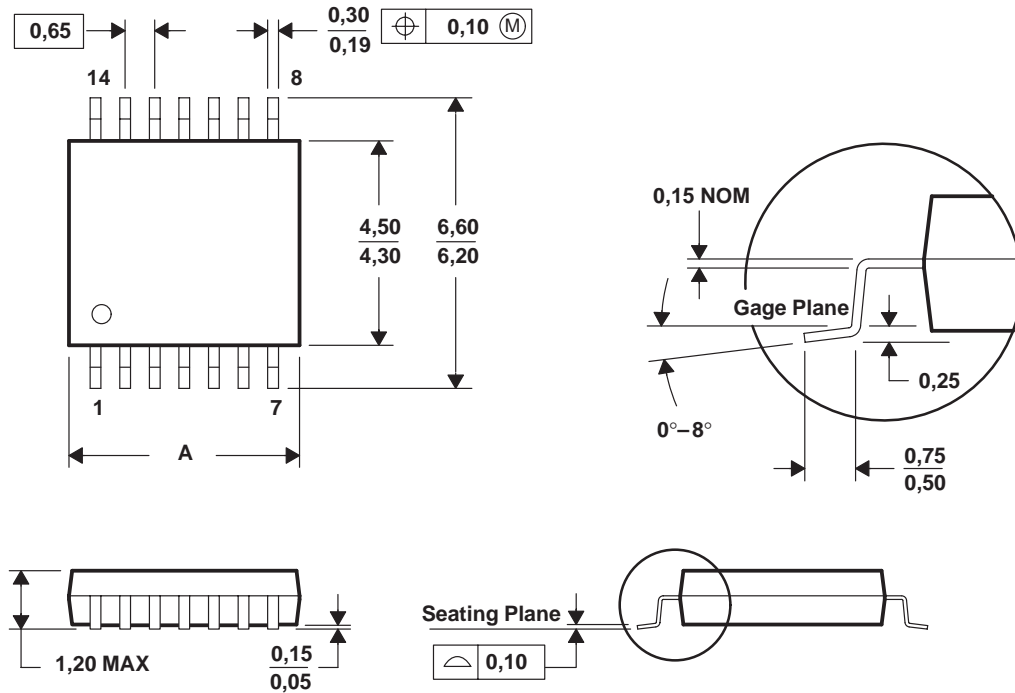
# MECHANICAL DATA

MTSS001C – JANUARY 1995 – REVISED FEBRUARY 1999

PW (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



PINS ** DIM	8	14	16	20	24	28
A MAX	3,10	5,10	5,10	6,60	7,90	9,80
A MIN	2,90	4,90	4,90	6,40	7,70	9,60

4040064/F 01/97

- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
  - D. Falls within JEDEC MO-153

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